SN54153, SN54LS153, SN54S153 SN74153, SN74LS153, SN74S153 JE DATA SELECTORS/MULTIPLEYERS

DECEMBER 1972 - REVISED MARCH 1988

DUAL 4-LINE TO 1-LINE DATA SELECTORS/MULTIPLEXERS

Permits Multiplexing from N lines to 1 line

- Performs Parallel-to-Serial Conversion
- Strobe (Enable) Line Provided for Cascading (N lines to n lines)
- High-Fan-Out, Low-Impedance, Totem-Pole Outputs
- Fully Compatible with most TTL Circuits

TYPE	•	TYPICAL AVERAGE PROPAGATION DELAY TIMES				
	FROM DATA	FROM STROBE	FROM SELECT	DISSIPATION		
153	14 ns	17 ns	22 ns	180 mW		
LS153	14 ns	19 ns	22 ns	31 mW		
'S153	6 ns	9.5 ns	12 ns	225 mW		

description

Each of these monolithic, data selectors/multiplexers contains inverters and drivers to supply fully complementary, on-chip, binary decoding data selection to the AND-OR gates. Separate strobe inputs are provided for each of the two four-line sections.

FUNCTION TABLE

F	-ECT PUTS		ATA	NPUT:	\$	STROBE	OUTPUT
В	Α	CO	C1	C2	C3	Ğ	Y
×	×	X	X	Х	×	н	_
) L	L	L	X	X	X	L	L
L	L	Н	Х	X	х	L	н
L	Н	х	L	X	X	L	L
L	н	×	Н	х	×	L	н
Н	L	х	X	L	x	L	L
Н	L	х	X	Н	×	Ļ	н
н	н	×	х	Х	ᆫ	L	L
н	н	х	X	Х	н	L	н

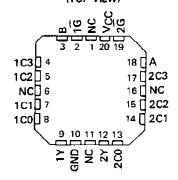
Select inputs A and B are common to both sections.

H = high level, L = low level, X = irrelevant

SN54153, SN54LS153, SN54S153...J OR W PACKAGE SN74153...N PACKAGE SN74LS153, SN74S153...D OR N PACKAGE (TOP VIEW)

1 <u>G</u> [_ 1	U ₁₆	□ vcc
в[2	15	□ 2G
1C3 []3	14	□ A
1C2[]4	13	2C3
101]5	12	2C2
1 CO [6	11	2C1
1Y 🛚	7	10	200
GND [8	9] 2Y

SN54LS153, SN54S153...FK PACKAGE (TOP VIEW)



NC - No internal connection

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

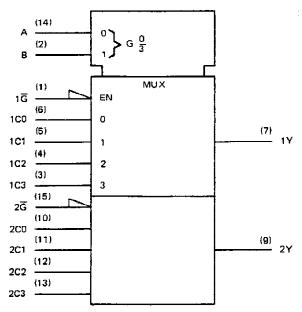
Supply voltage, VCC (See Note 1)
Input voltage: '153, 'S153 5.5 V
L\$153 7 V
Operating free-air temperature range: SN54'55°C to 125°C
SN74'
Storage temperature range65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

PRODUCTION DATA documents contain information current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

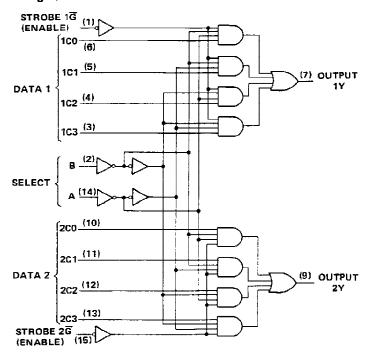


logic symbol†



[†]This symbol is in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.

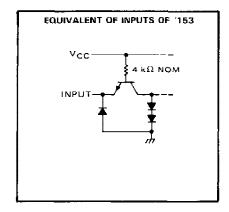
logic diagrams (positive logic)

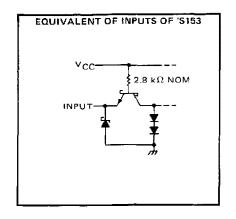


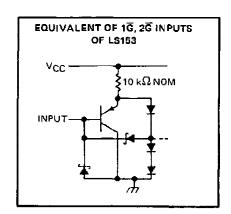
Pin numbers shown are for D, J, N, and W packages.

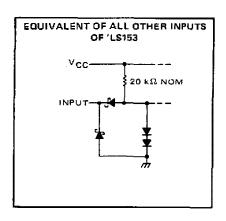


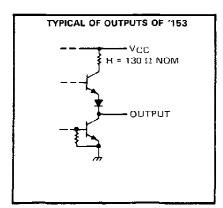
schematics of inputs and outputs

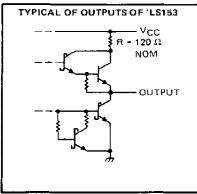


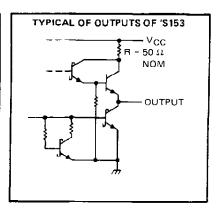












SN54153, SN74153 DUAL 4-LINE TO 1-LINE DATA SELECTORS/MULTIPLEXERS

recommended operating conditions

		SN54153			SN74153		
	MIN	NOM	MAX	MIN	NOM	NOM MAX	UNIT
Supply voltage, V _{CC}	4.5	5	5.5	4.75	5	5.25	V
High-level output current, IOH			-800			-800	μД
Low-level output current, IOL			16		·	16	mA
Operating free-air temperature, TA	-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

			:	SN5415	3		SN7415	3	UNIT
	PARAMETER	TEST CONDITIONS [†]	MIN	TYP‡	MAX	MIN	TYP‡	MAX	UNIT
VIH	High-level input voltage		2			2			٧
VIL	Low-level input voltage				8.0			8.0	V
Vik	Input clamp voltage	V _{CC} = MIN, I ₁ = -12 mA			-1.5			-1.5	V
Voн	High-level output voltage	V _{CC} = MIN, V _{IH} = 2 V, V _{IL} = 0.8 V, I _{OH} = -800 μA	2.4	3.4		2.4	3.4		٧
VOL	Low-level output voltage	V _{CC} = MIN, V _{IH} = 2 V, V _{IL} = 0.8 V. I _{OL} = 16 mA		0.2	0.4		0.2	0.4	٧
tı	Input current at maximum input voltage	V _{CC} = MAX, V _I = 5.5 V			1			1	mA
ЧН	High-level input current	V _{CC} = MAX, V _I = 2.4 V			40			40	μΑ
ЦL	Low-level input current	V _{CC} = MAX, V _I = 0.4 V			-1.6	ľ		-1.6	mA
los	Short-circuit output current §	V _{CC} = MAX	-20		55	-18		-57	mA
ICCL	Supply current, output fow	V _{CC} = MAX, See Note 2		36	52		36	60	mA

[†]For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

switching characteristics, VCC = 5 V, T_A = 25 $^{\circ}$ C

	FROM	то	TEST CONDITIONS	MIN T	YP MAX	UNIT
PARAMETER¶	(INPUT)	(OUTPUT)	TEST CONDITIONS	IVIVIO I	TE MAA	ONT
tPLH	Data	Y			12 18	ns
tpHL	Data	Y	1		15 23	ns
tpLH	Select	Y	CL = 30 pF, RL = 400 Ω,		22 34	ns
¹PHL	Select	Y	See Note 3		22 34	⊓\$
^t PLH	Strobe G	Y	7		19 30	กร
tPHL	Strobe G	Y			15 23	กร

 $[\]mathbf{1}_{\text{tPLH}}$ = propagation delay time, low-to-high-level output

 $^{^{\}ddagger}$ All typical values are at $^{\lor}$ CC = 5 $^{\lor}$ C.

Not more than one output should be shorted at a time.

NOTE 2: I_{CCL} is measured with the outputs open and all inputs grounded.

tpHL = propagation delay time, high-to-low-level output

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

recommended operating conditions

		s	SN54LS153			SN74L\$153			
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
Vcc	Supply voltage	4.5	5	5,5	4.75	5	5.25	٧	
νін	High-level input voltage	2			2			٧	
VIL	Low-level input voltage			0.7			0.8	V	
ЮН	High-level output current			- 0.4			- 0.4	mΑ	
loL	Low-level output current			4			8	mA	
TA	Operating free-air temperature	55		125	Ö		70	°C	

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS †		S	N54LS1	53	s	N74LS1	53	UNIT
PARAMETER	TEST CONDITIONS V			TYP‡	YP‡ MAX		TYP‡	MAX	UNII
ViK	V _{CC} = MIN, I ₁ = - 18 mA				- 1.5			– 1.5	V
Voн	V _{CC} = MIN, V _{IH} = 2V, V _{IL} = MAX l _{OH} = -0.4 mA		2.5	3.4		2,7	3.4	•	٧
Va.	V _{CC} = MIN, V _{IH} = 2 V,	IOL = 4 mA		0.25	0.4		0.25	0.4	
VOL	VIL = MAX,	I _{OL} = 8 mA]				0.35	0.5	٧
lţ	VCC = MAX, VI = 7 V				0.1			0.1	mΑ
ltH	V _{CC} = MAX, V ₁ = 2.7 V	•			20			20	μА
1G, 2G	V _{CC} = MAX, V _I = 0.4 V				- 0.2			-0.2	mA
All other	VCC - MAX, VI - 0.4 V				- 0.4			- 0.4	mA
ios §	Vcc = MAX		20		— 100	- 20		- 100	mΑ
1CCL	V _{CC} = MAX, See Note 2			6.2	10		6.2	10	πΑ

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

NOTE 2: ICCL is measured with the outputs open and all inputs grounded.

switching characteristics, V_{CC} = 5 V, T_A = 25°C

PARAMETER¶	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
tрLH	Data	Y			10	15	ns
tpHL.	Data	Y	CL = 15 pF,		17	26	пѕ
tPLH .	Select	V	R _L = 2 kΩ,		19	29	пѕ
tPHL	Select	Υ	See Note 3		25	38	ns
t P LH	Strobe G	Y	300 NO.6 3		16	24	ns
^t PHL	Strabe G	Y			21	32	ns

 $[\]P_{\text{tpLH}}$ = propagation delay time, low-to-high-level output

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

[‡] All typical values are at V_{CC} = 5 V, T_A = 25°C.

[§]Not more than one output should be shorted at a time.

tpHL = propagation delay time, high-to-low-level output

SN54S153, SN74S153 DUAL 4-LINE TO 1-LINE DATA SELECTORS/MULTIPLEXERS

recommended operating conditions

	S	SN54S153			SN74S153		
	MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Supply voltage, VCC	4.5	5	5.5	4.75	5	5.25	٧
High-level output current, IOH			-1			-1	mΑ
Low-level output current, IOL			20			20	mA
Operating free-air temperature, TA	-55		125	0		70	,C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER	TEST CONDITIONS†	MIN	TYP ‡	MAX	UNIT
VIH	High-level input voltage		2			٧
VIL	Low-level input voltage				0.8	٧
ViK	Input clamp voltage	V _{CC} = MIN, I ₁ = -18 mA			-1.2	٧
	111-le le el outeut voltere	V _{CC} = MIN, V _{IH} = 2 V, Series 545	2.5	3.4		V
∨он	High-level output voltage	V _{IL} = 0.8 V, I _{OH} = -1 mA Series 745	2,7	3.4		v
٧	Low-level output voltage	V _{CC} = MIN, V _{IH} = 2 V,	1		0.5	V
VOL	Low-level output vortage	V _{IL} = 0.8 V, I _{OL} = 20 mA				L
ų	Input current at maximum input voltage	V _{CC} = MAX, V _I = 5.5 V			1	mΑ
ΊΗ	High-level input current	V _{CC} = MAX, V ₁ = 2.7 V			50	μA
1 ₁ L	Low-level input current	V _{CC} = MAX, V _I = 0.5 V			-2	mA
los	Short-circuit output current	V _{CC} = MAX	-40		-100	mΑ
icci.	Supply current, low-level output	V _{CC} = MAX, See Note 2	1	45	70	mΑ

[†]For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

switching characteristics, VCC = 5 V, TA = 25°C

PARAMETER¶	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
^t PLH	Data	Y			6	9	ns
†PHL	Data	Y	7		6	9	ns
tPLH .	Select	Y	CL = 15 pF, RL = 280 Ω,		11.5	18	пѕ
tPHL.	Select	Y	See Note 3		12	18	ns
tРLН	Strobe G	Y	7		10	15	nş
ФHL	Strobe Ĝ	Y	7		9	13.5	ns

TtpLH = propagation delay time, low-to-high-level output

[‡]All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25 ^{\circ}\text{C}$.

 $[\]S$ Not more than one output should be shorted at a time and duration of short-circuit should not exceed one second.

NOTE 2: ${}^{\dagger}_{CCL}$ is measured with the outputs open and all inputs grounded,

tpHL = propagation delay time, high to-low level output

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
76011012A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	N / A for Pkg Type
7601101EA	ACTIVE	CDIP	J	16	1	TBD	Call TI	N / A for Pkg Type
7601101EA	ACTIVE	CDIP	J	16	1	TBD	Call TI	N / A for Pkg Type
7601101FA	ACTIVE	CFP	W	16	1	TBD	Call TI	N / A for Pkg Type
7601101FA	ACTIVE	CFP	W	16	1	TBD	Call TI	N / A for Pkg Type
JM38510/07902BEA	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI
JM38510/07902BEA	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI
JM38510/07902BFA	OBSOLETE	CFP	W	16		TBD	Call TI	Call TI
JM38510/07902BFA	OBSOLETE	CFP	W	16		TBD	Call TI	Call TI
JM38510/30902B2A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	N / A for Pkg Type
JM38510/30902B2A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	N / A for Pkg Type
JM38510/30902BEA	ACTIVE	CDIP	J	16	1	TBD	Call TI	N / A for Pkg Type
JM38510/30902BEA	ACTIVE	CDIP	J	16	1	TBD	Call TI	N / A for Pkg Type
SN54153J	ACTIVE	CDIP	J	16	1	TBD	Call TI	N / A for Pkg Type
SN54153J	ACTIVE	CDIP	J	16	1	TBD	Call TI	N / A for Pkg Type
SN54LS153J	ACTIVE	CDIP	J	16	1	TBD	Call TI	N / A for Pkg Type
SN54LS153J	ACTIVE	CDIP	J	16	1	TBD	Call TI	N / A for Pkg Type
SN54S153J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI
SN54S153J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI
SN74153N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74153N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74LS153D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS153D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS153DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS153DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS153DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS153DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS153DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS153DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS153J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI
SN74LS153J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI
SN74LS153N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS153N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS153N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI





.com 12-Jan-2006

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74LS153NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS153NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS153NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS153NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS153NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS153NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S153D	OBSOLETE	SOIC	D	16		TBD	Call TI	Call TI
SN74S153D	OBSOLETE	SOIC	D	16		TBD	Call TI	Call TI
SN74S153N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74S153N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74S153N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74S153N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SNJ54153J	ACTIVE	CDIP	J	16	1	TBD	Call TI	N / A for Pkg Type
SNJ54153J	ACTIVE	CDIP	J	16	1	TBD	Call TI	N / A for Pkg Type
SNJ54153W	ACTIVE	CFP	W	16	1	TBD	Call TI	N / A for Pkg Type
SNJ54153W	ACTIVE	CFP	W	16	1	TBD	Call TI	N / A for Pkg Type
SNJ54LS153FK	ACTIVE	LCCC	FK	20	1	TBD	Call TI	N / A for Pkg Type
SNJ54LS153FK	ACTIVE	LCCC	FK	20	1	TBD	Call TI	N / A for Pkg Type
SNJ54LS153J	ACTIVE	CDIP	J	16	1	TBD	Call TI	N / A for Pkg Type
SNJ54LS153J	ACTIVE	CDIP	J	16	1	TBD	Call TI	N / A for Pkg Type
SNJ54LS153W	ACTIVE	CFP	W	16	1	TBD	Call TI	N / A for Pkg Type
SNJ54LS153W	ACTIVE	CFP	W	16	1	TBD	Call TI	N / A for Pkg Type
SNJ54S153FK	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI
SNJ54S153FK	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI
SNJ54S153J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI
SNJ54S153J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI
SNJ54S153W	OBSOLETE	CFP	W	16		TBD	Call TI	Call TI
SNJ54S153W	OBSOLETE	CFP	W	16		TBD	Call TI	Call TI

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.



PACKAGE OPTION ADDENDUM

12-Jan-2006

package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

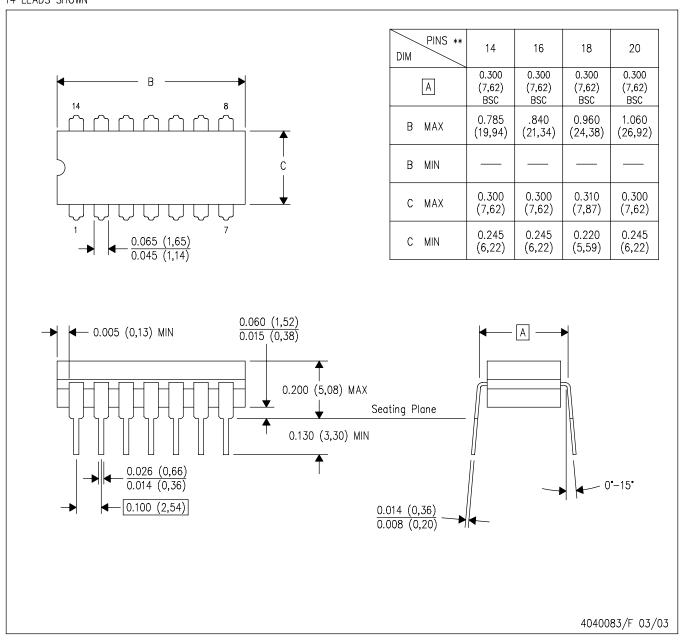
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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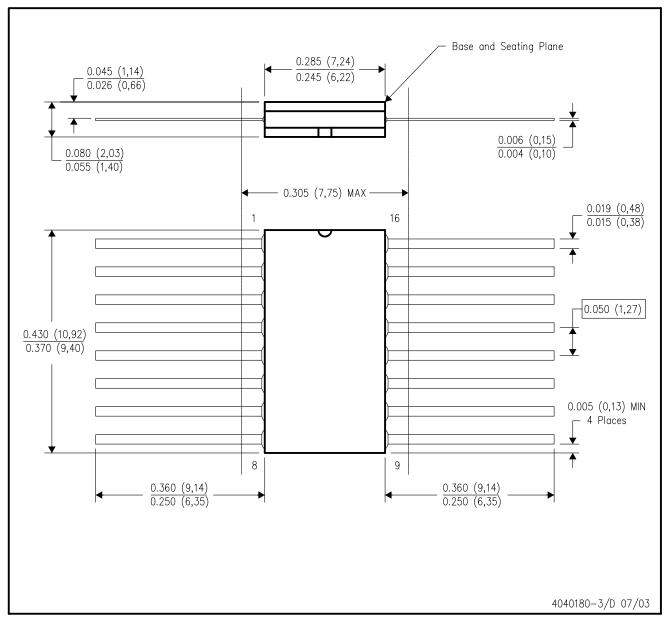
14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F16)

CERAMIC DUAL FLATPACK



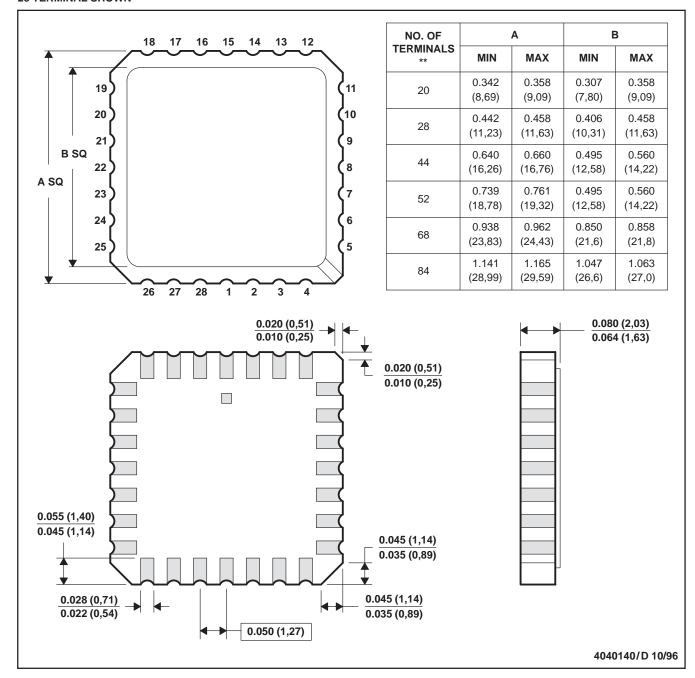
- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F16 and JEDEC MO-092AC



FK (S-CQCC-N**)

28 TERMINAL SHOWN

LEADLESS CERAMIC CHIP CARRIER



NOTES: A. All linear dimensions are in inches (millimeters).

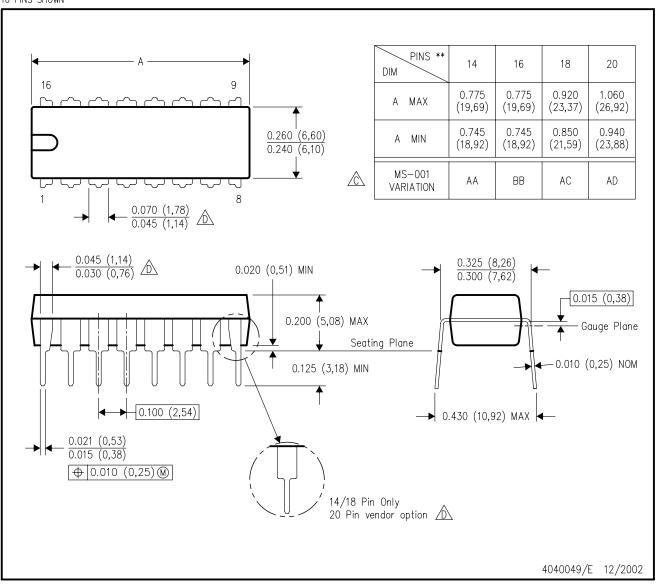
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN

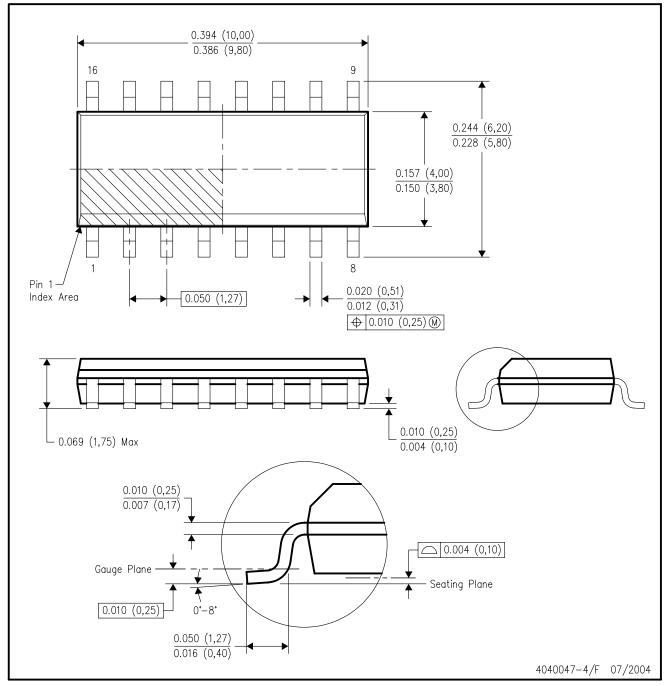


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-012 variation AC.

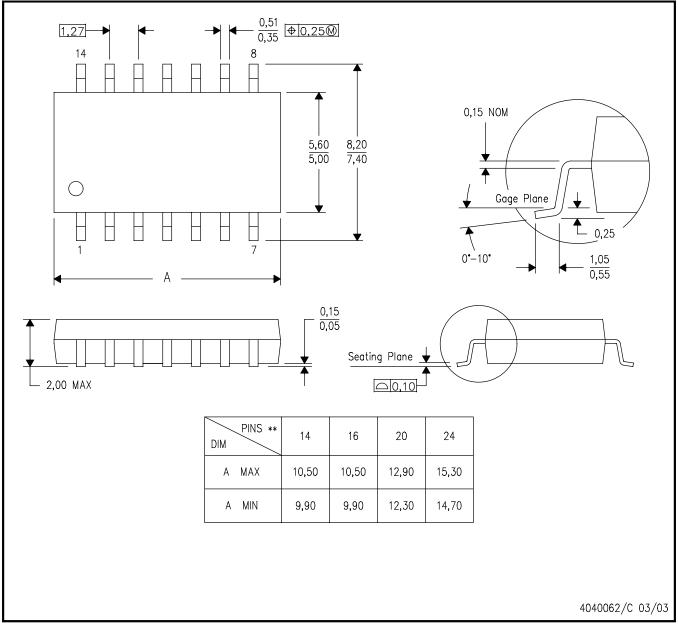


MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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